

Amendments to the Claims

Listing of Claims:

Claims 1 - 13.

Claim 14 (new). An optical module, comprising:

a circuit carrier;

a non-packaged semiconductor device flip-chip mounted on said circuit carrier;

a lens unit disposed for projecting electromagnetic radiation onto said semiconductor device, said lens unit including a lens holder and a lens assembly with at least one lens; and

said circuit carrier having at least one relatively thin region and a relatively thick region supporting said thin region.

Claim 15 (new). The optical module according to claim 14, wherein said lens holder is supported in said thin region of said circuit carrier.

Claim 16 (new). The optical module according to claim 14, wherein said semiconductor device is disposed in or adjacent said thin region of said circuit carrier.

Claim 17 (new). The optical module according to claim 14, wherein said thick region is at least partially U-shaped, L-shaped, F-forked, or E-forked or frame-shaped.

Claim 18 (new). The optical module according to claim 14, wherein said thick region is a rigid portion of said circuit carrier.

Claim 19 (new). The optical module according to claim 18, wherein said

thick region is a rigid portion of a multilayer printed circuit board.

Claim 20 (new). The optical module according to to claim 18, wherein said thick region is a rigid portion of an FR4 circuit board.

Claim 21 (new). The optical module according to to claim 14, wherein said thin region is a recessed or milled-out portion of said circuit carrier.

Claim 22 (new). The optical module according to to claim 14, wherein said thin region and said thick region are implemented as a molded interconnect device with integrated conductor tracks.

Claim 23 (new). The optical module according to to claim 14, wherein said thin region is a flexible printed circuit board and said thick region is a rigid printed circuit board.

Claim 24 (new). The optical module according to to claim 14, which further comprises support elements at least partially formed on said lens holder.

Claim 25 (new). The optical module according to to claim 14, wherein said lens holder is connected, in particular glued, laser-welded, screwed or riveted, to said circuit carrier, preferably adjacently to the support elements.

Claim 26 (new). The optical module according to to claim 25, wherein said lens holder is glued, laser-welded, screwed, or riveted to said circuit carrier.

Claim 27 (new). The optical module according to to claim 25, wherein said lens holder is connected to said circuit carrier adjacent support elements mounted to said lens holder.

Claim 28 (new). The optical module according to to claim 14, wherein said thick region of said circuit carrier forms a part of said lens unit.

Claim 29 (new). The optical module according to claim 28, wherein said thick region of said circuit carrier forms a part of said lens holder and said lens holder is an MID (molded interconnect device) with integrated conductor tracks.

Claim 30 (new). The optical module according to claim 14, wherein:

said semiconductor device is disposed on a side of said circuit carrier facing away from said lens unit; and

said thin region of said circuit carrier is formed with an opening enabling through-projection of electromagnetic radiation from said lens assembly onto said semiconductor device.

Claim 31 (new). An optical system, comprising at least one optical module according to claim 14.